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Latest Advances in Grinding Technology

Guest Editor:

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Deadline for manuscript submissions:

closed (15 November 2021)

Message from the Guest Editor

Dear Colleagues,

This Special Issue on the will highlight state-of-the-art advances in grinding technology. It is an operation that is difficult to avoid with respect to the manufacturing of hard materials and in the production of complex three-dimensional shapes.

It will cover the following avenues:

- 1. The use of nanotechnology in grinding operations;
- 2. The use of neural networks and artificial intelligence in optimizing the grinding process;
- 3. The use of ultrasound wave technology during the process of grinding;
- The new techniques in dressing operations for expensive diamond and other highly advanced grinding wheels;
- 5. The latest techniques and investigations in coolant usage and operations;
- 6. Ultra-precision grinding operations;
- Latest techniques for in-process grinding monitoring to achieve high-precision, highefficiency, and low-cost operations;
- 8. Optical and aero-mechanical profiling of grinding surface topography profiling;
- 9. Process modeling and theoretical background of the heat transfer aspects of the grinding process.

For more information, please clink: mdpi.com/si/54508.

Dr. Talal Maksoud *Guest Editor*











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Message from the Editor-in-Chief

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